

N-Channel Enhancement Mode Power MOSFET

Description

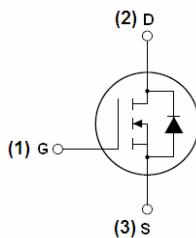
The PE0213 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- $V_{DS} = 200V, I_D = 13A$
- $R_{DS(ON)} < 140m\Omega @ V_{GS}=10V$ (Typ:123m Ω)
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Boost converters
- LED backlighting
- Uninterruptible power supply



Schematic diagram



TO-220-3L top view

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage	200	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous	13	A
$I_D (100^\circ C)$	Drain Current-Continuous($T_C=100^\circ C$)	9	A
I_{DM}	Pulsed Drain Current	45	A
P_D	Maximum Power Dissipation	95	W
	Derating factor	0.6	W/ $^\circ C$
E_{AS}	Single pulse avalanche energy ^(Note 5)	200	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^\circ C$

Thermal Characteristic

R_{JJC}	Thermal Resistance, Junction-to-Case ^(Note 2)	1.6	°C/W
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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	200	-	-	V
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=200\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics ^(Note 3)						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	3	4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	-	123	140	$\text{m}\Omega$
G_{FS}	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=8\text{A}$	-	6	-	S
Dynamic Characteristics ^(Note 4)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2000	-	PF
C_{oss}	Output Capacitance		-	260	-	PF
C_{rss}	Reverse Transfer Capacitance		-	150	-	PF
Switching Characteristics ^(Note 4)						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=100\text{V}, R_{\text{G}}=8\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	-	11.5	-	nS
t_r	Turn-on Rise Time		-	22	-	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		-	18	-	nS
t_f	Turn-Off Fall Time		-	10	-	nS
Q_g	Total Gate Charge	$V_{\text{DS}}=160\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=10\text{V}$	-	27	-	nC
Q_{gs}	Gate-Source Charge		-	4.4	-	nC
Q_{gd}	Gate-Drain Charge		-	11.6	-	nC
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage ^(Note 3)	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=8\text{A}$	-	-	1.2	V
I_{S}	Diode Forward Current ^(Note 2)	-	-	-	13	A
t_{rr}	Reverse Recovery Time	$T_J = 25^\circ\text{C}, IF = 8\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ ^(Note 3)	-	32	-	nS
Q_{rr}	Reverse Recovery Charge		-	53	-	nC
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_j=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

Typical Electrical and Thermal Characteristics (Curves)

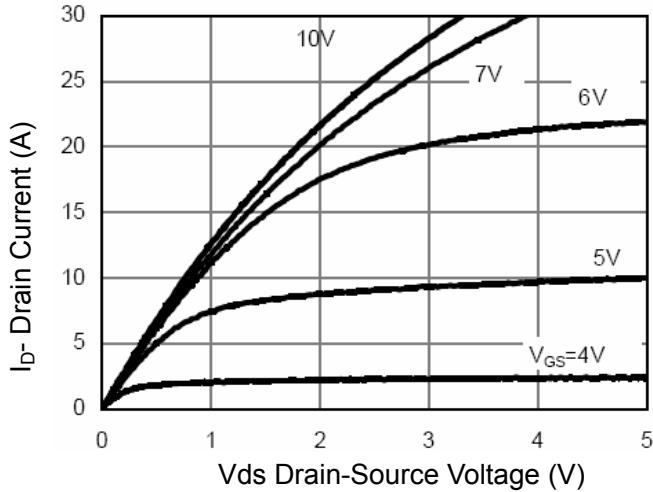


Figure 1 Output Characteristics

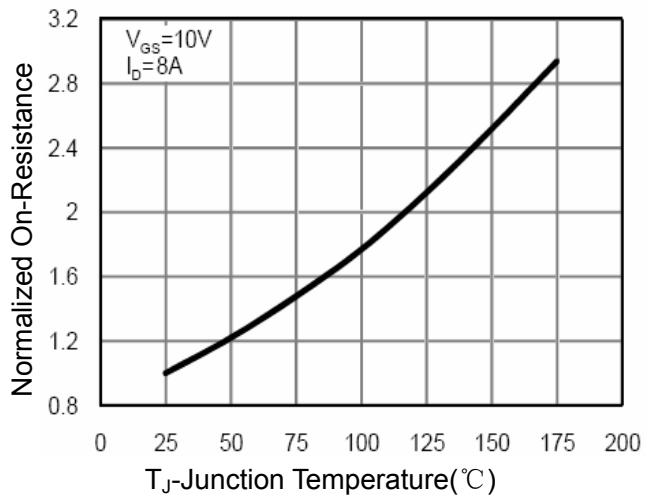


Figure 4 R_{DSON} -Junction Temperature

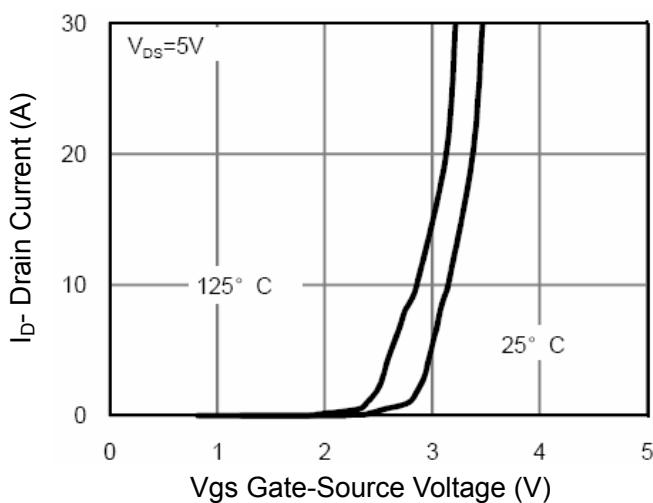


Figure 2 Transfer Characteristics

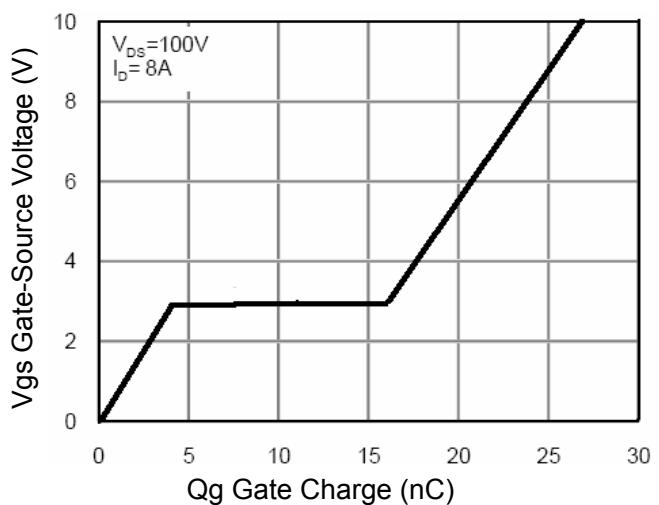


Figure 5 Gate Charge

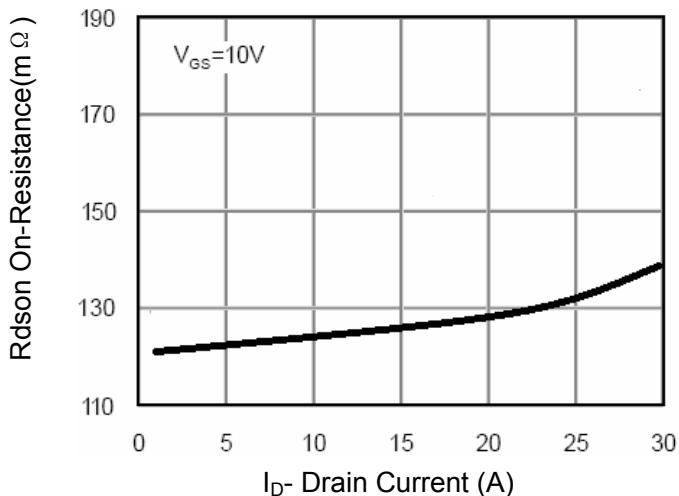


Figure 3 R_{DSON} - Drain Current

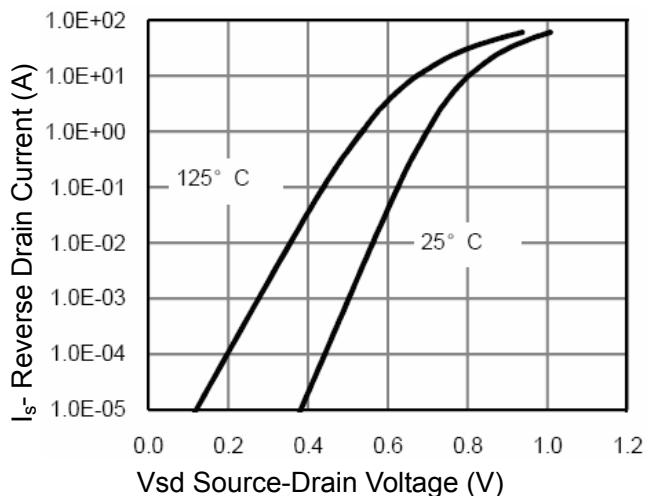


Figure 6 Source- Drain Diode Forward

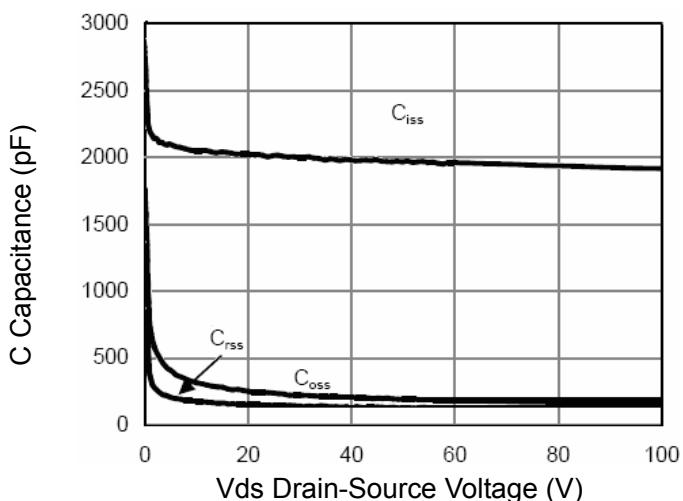


Figure 7 Capacitance vs Vds

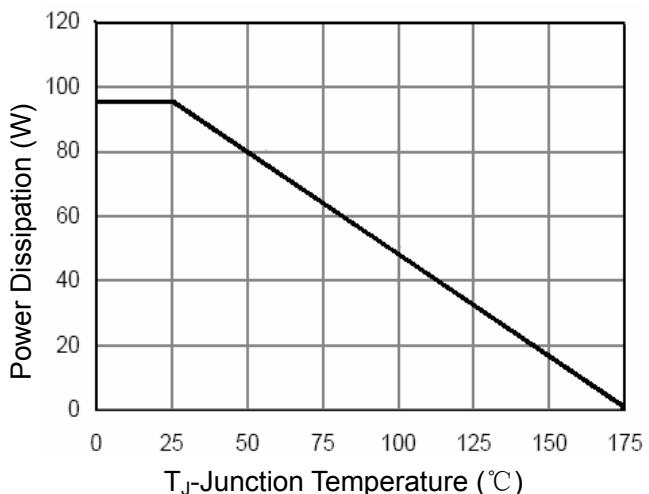


Figure 9 Power De-rating

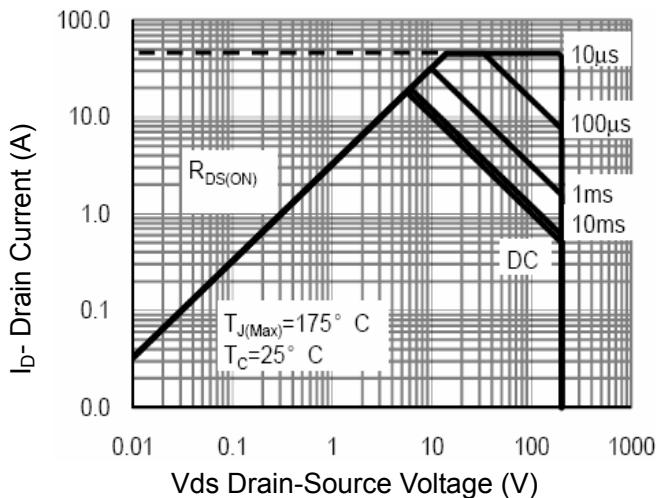


Figure 8 Safe Operation Area

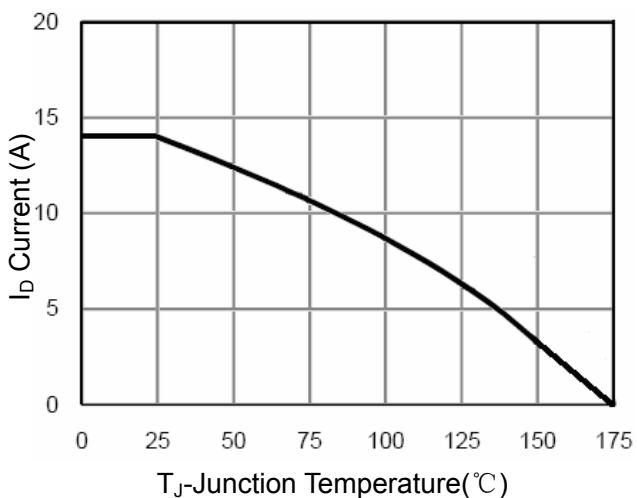


Figure 10 ID Current- Junction Temperature

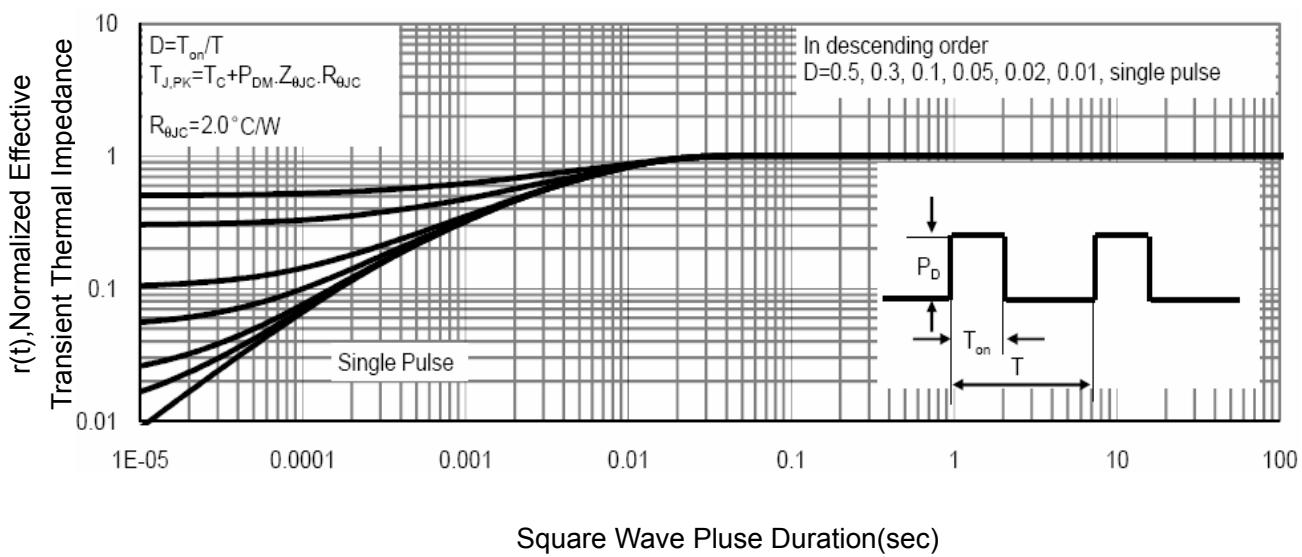
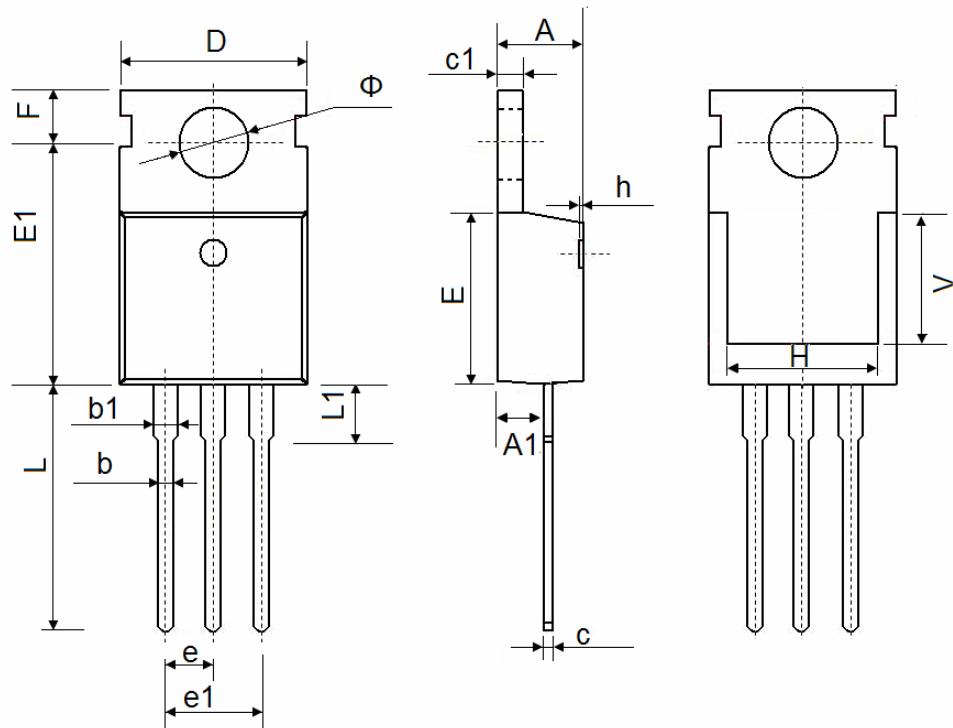


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150